

Tile Detector

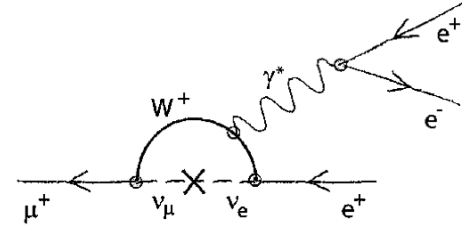
Mainz
March 8, 2018

Yonathan Munwes on behalf of the Tile Detector group



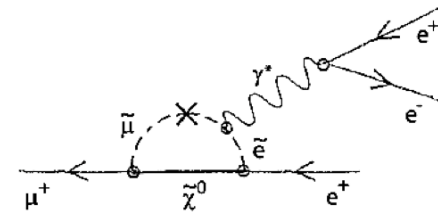
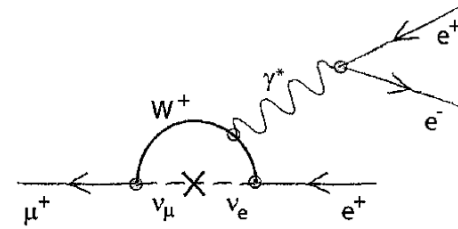
Introduction – signal

- Charged LFV $\mu^+ \rightarrow e^+ e^- e^+$
- SM Branching ratio **$< 10^{-54}$**
→ unobservable!

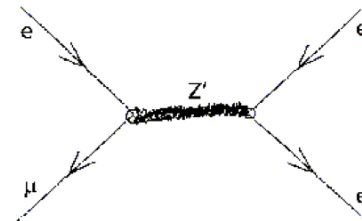


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- Enhanced in ($BR > 1 \times 10^{-16}$):
 - Grand unified models
 - Super symmetry
 - Left-right symmetric models
 - Extended Higgs sector
 - Extra dimensions (Kaluza-Klein tower)
 - ...



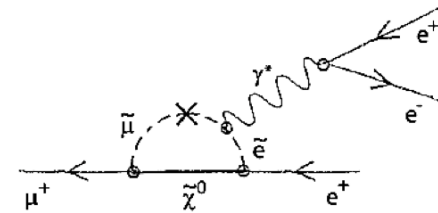
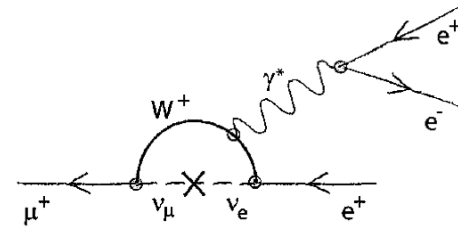
Loop diagram



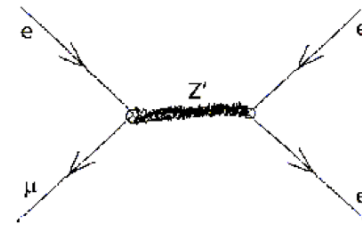
Tree level

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- Enhanced in ($BR > 1 \times 10^{-16}$):
 - Grand unified models
 - Super symmetry
 - Left-right symmetric models
 - Extended Higgs sector
 - Extra dimensions (Kaluza-Klein tower)
 - ...
- The current best limit $> 1 \times 10^{-12}$ (SINDRUM 1988)
- Mu3e experiment aims for $BR \sim 10^{-16}$



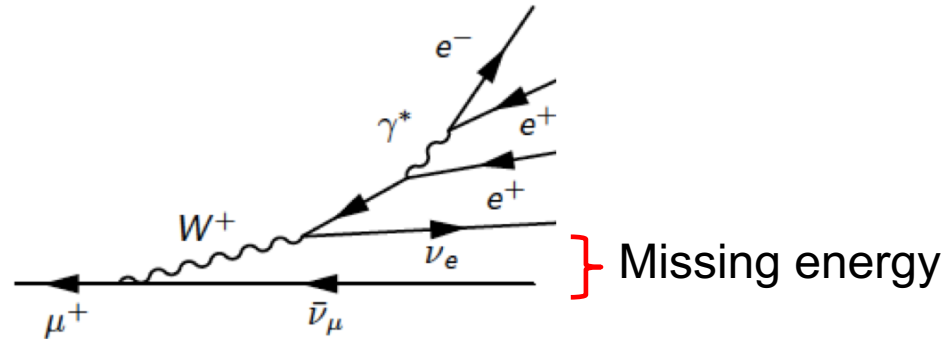
Loop diagram



Tree level

Background sources – internal conversion (irreducible)

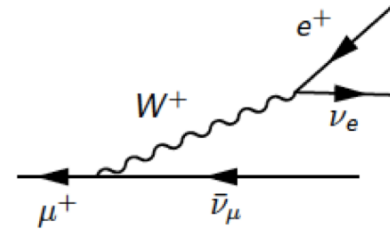
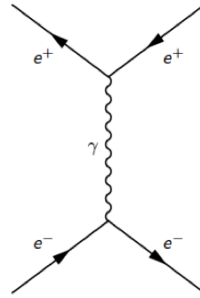
- Internal conversion in SM 3.4×10^{-5}



- Only distinguishing by missing momentum carried by neutrinos
- Need excellent momentum resolution!

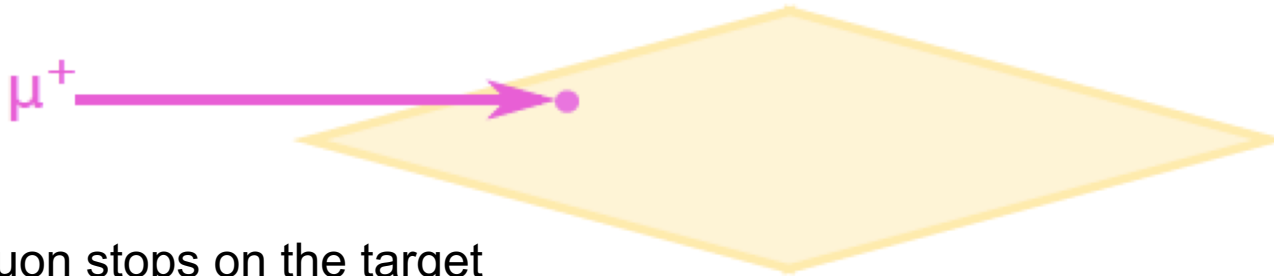
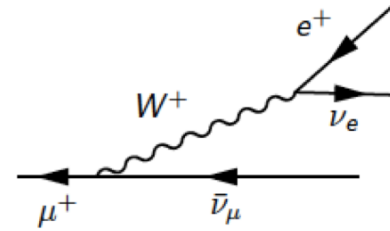
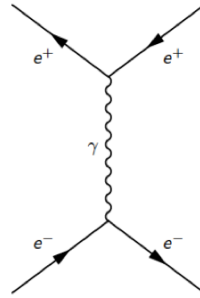
Background sources – accidental background

- Michel decay (SM 99.997%) – generating e^+
- Bhabha scattering
(e^+ scattering with e in the target)



Background sources – accidental background

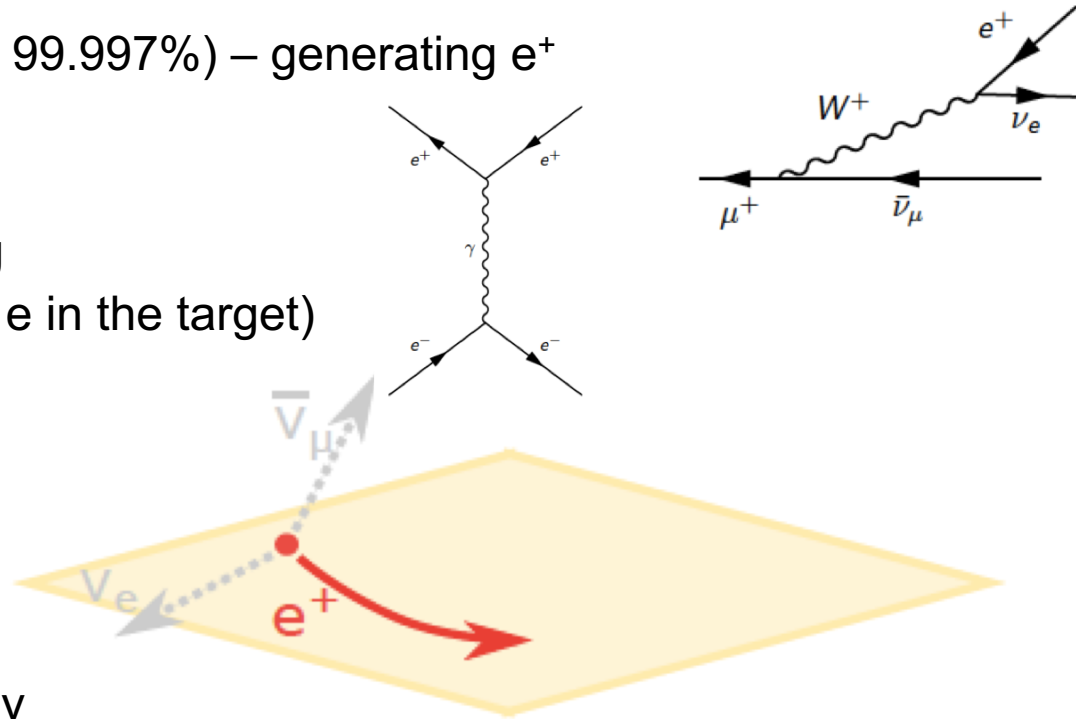
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Positive muon stops on the target

Background sources – accidental background

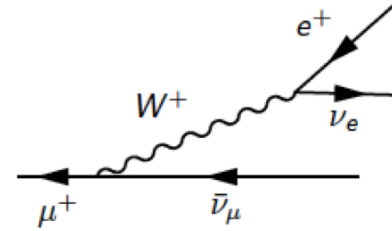
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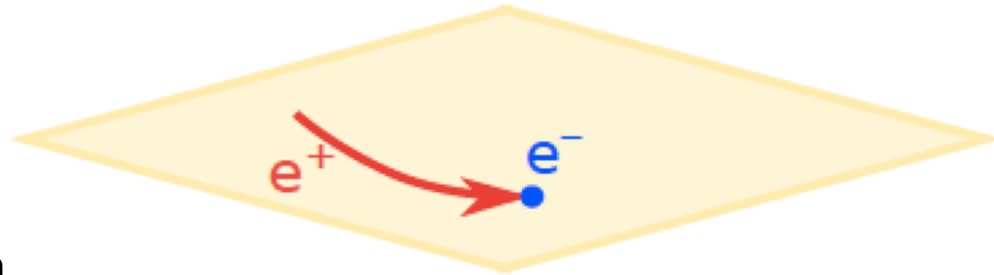
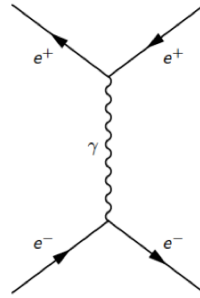
... Makes a Michel decay

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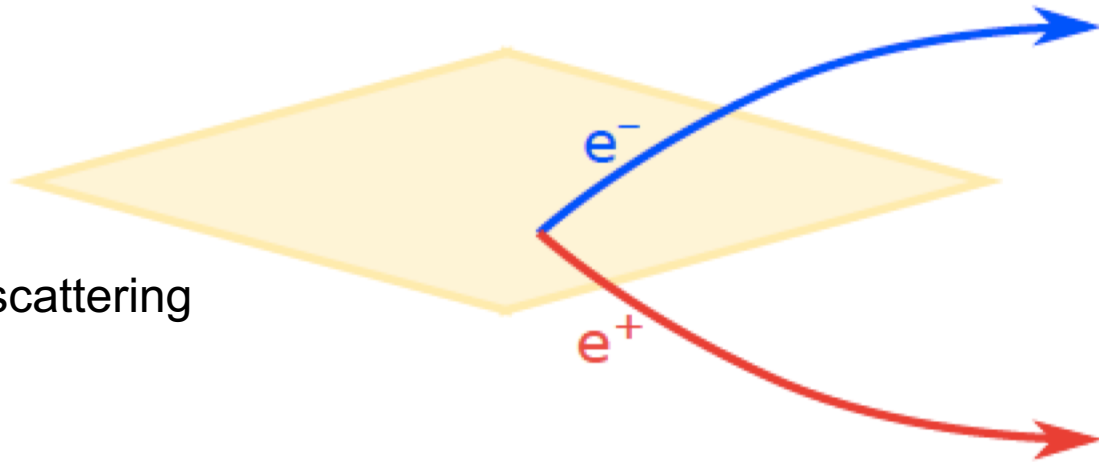
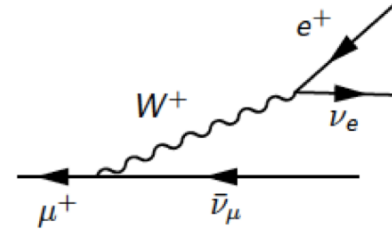
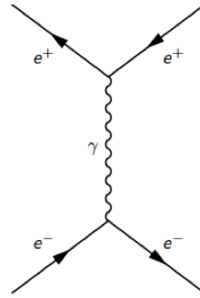
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(e^+ scattering with e in the target)



Positron hits an electron...

Background sources – accidental background

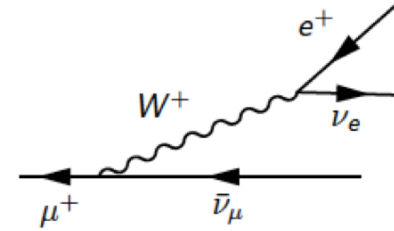
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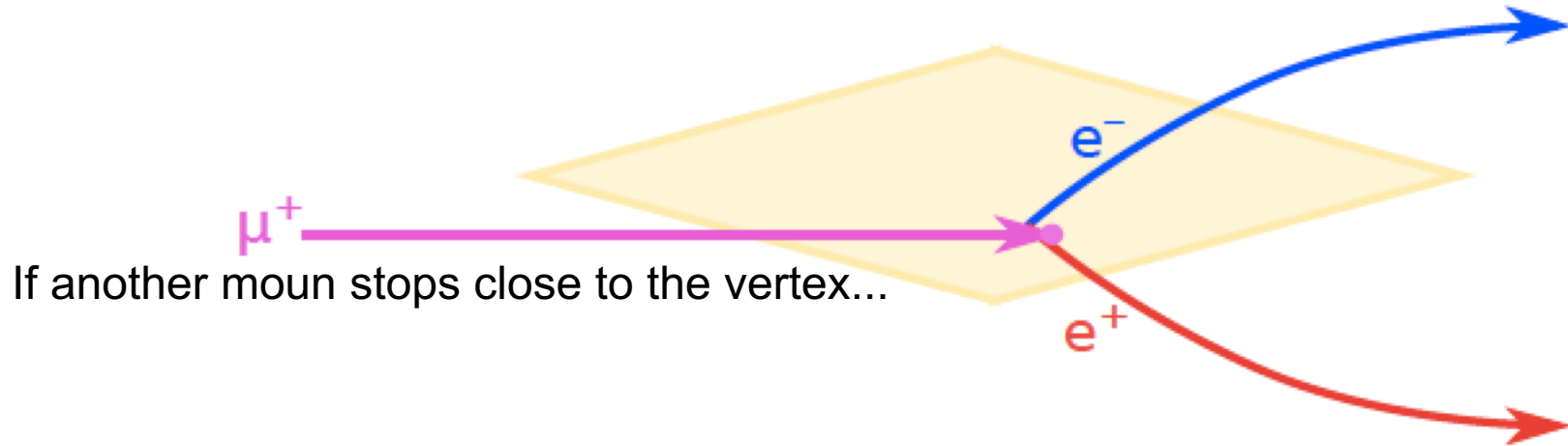
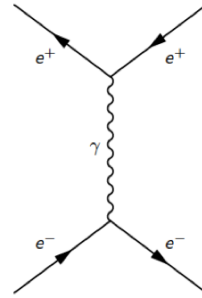
... Undergoing Bhabha scattering

Background sources – accidental background

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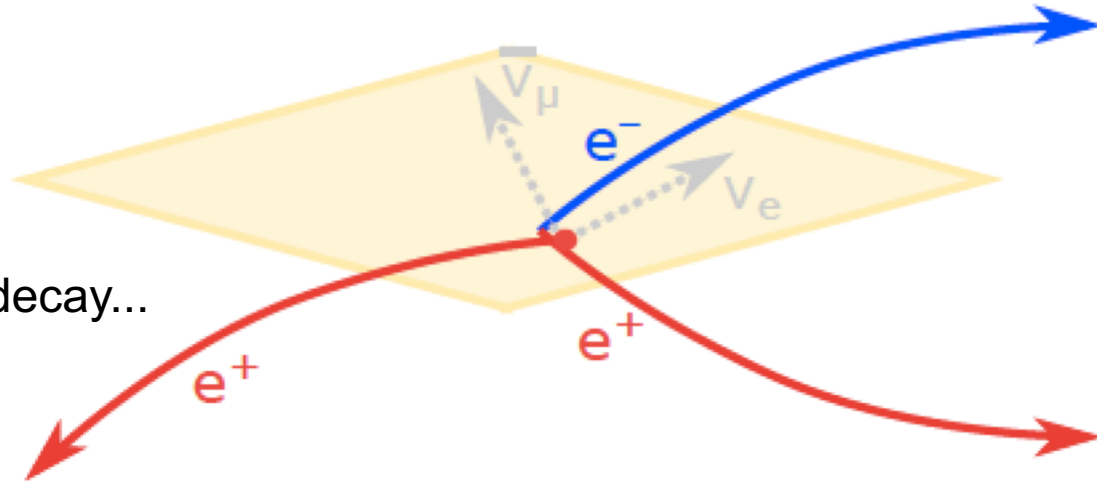
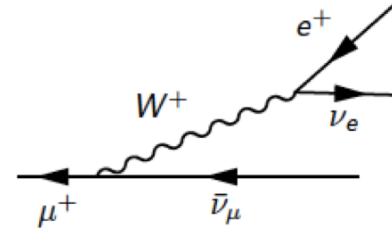
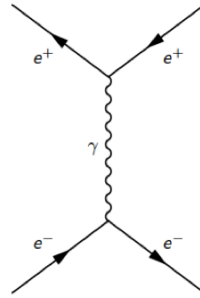


- Bhabha scattering
(e^+ scattering with e in the target)



Background sources – accidental background

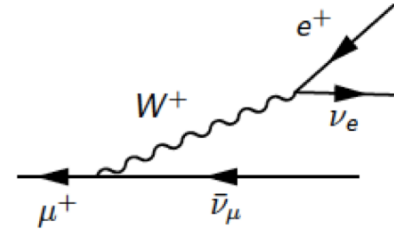
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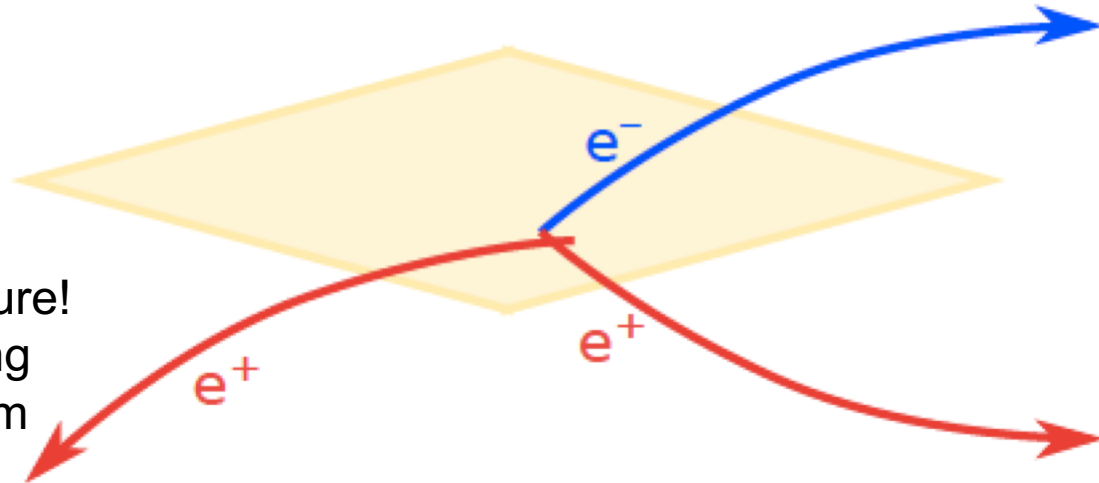
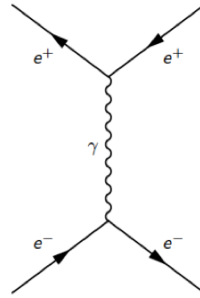
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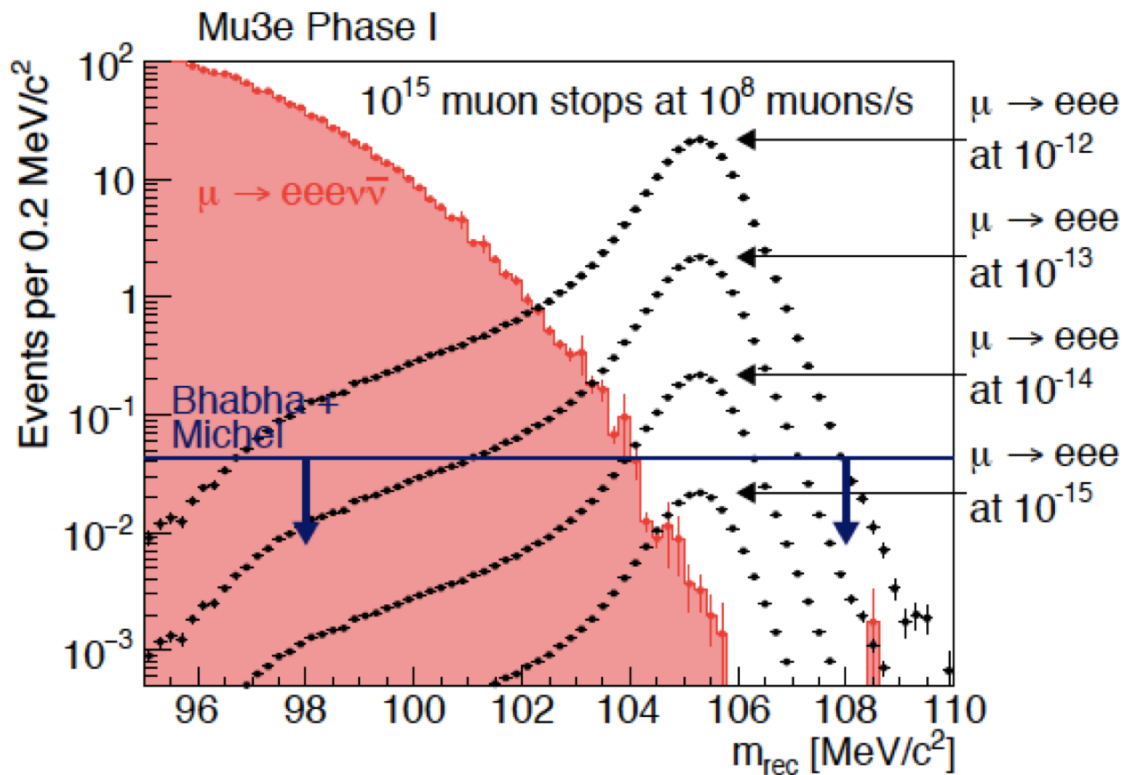
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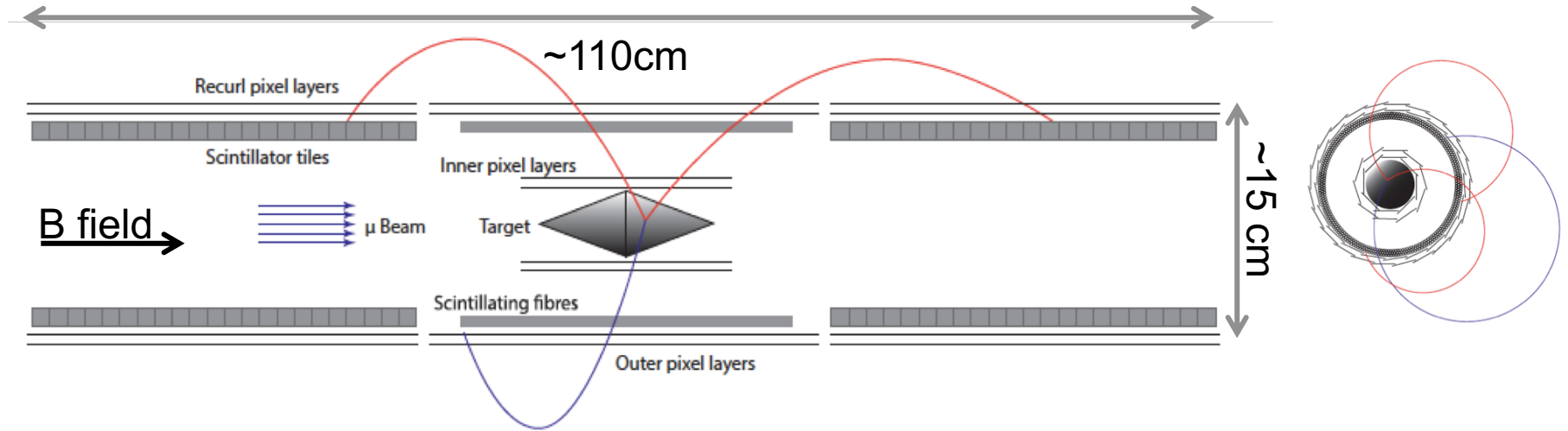
We got the basic signature!

- Need very good timing
- vertex and momentum resolution

Mass reconstruction



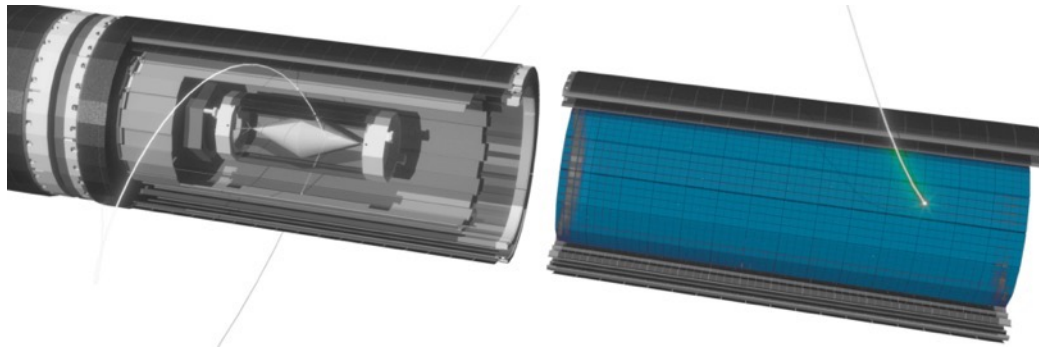
The Mu3e experiment - phase I



Key requirements:

- High muon stopping rate ($O(10^8$ muons/s))
- Vertex resolution $\sim 200 \mu\text{m}$
- Momentum resolution $\sim 0.5 \text{ MeV}$
- Require low material budget
- Fiber time resolution $< 500 \text{ ps}$ (accidental background suppression)
- Tile time resolution $< 100 \text{ ps}$ (coincidence and event separation)

The Tile detector



Requirements

- Detection efficiency close to 100%
- Time resolution better than 100 ps
- Maximum hit rate up to 60 kHz/channel
- Enough energy resolution for time walk correction

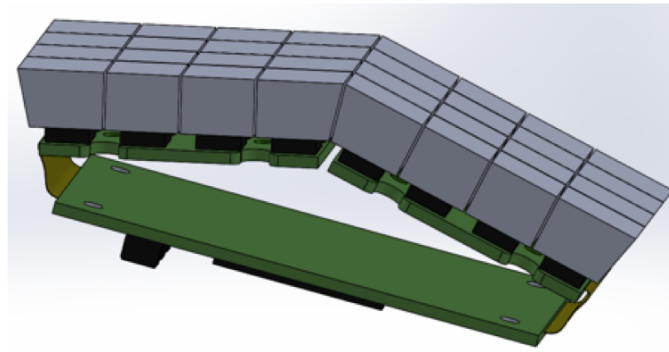
Background suppression factor

Tracker hits	Fibers	Tiles	Both
≥ 4	35	5.3	72
≥ 6	44	5.3	102

Detector overview

Submodule

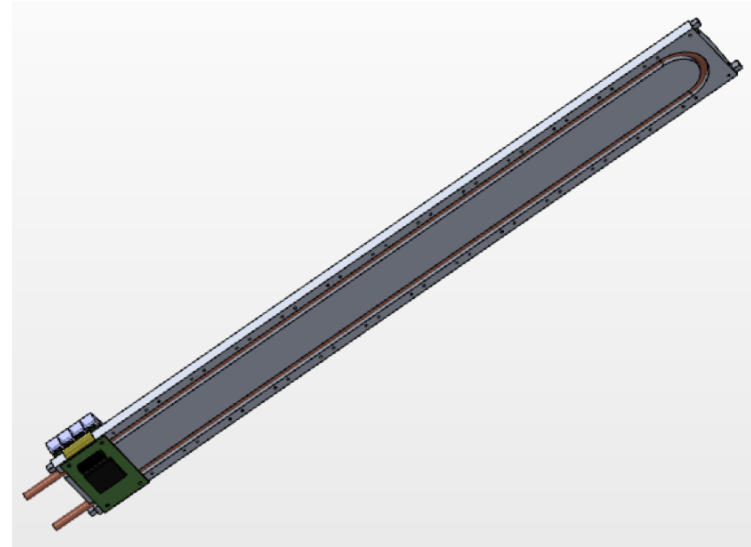
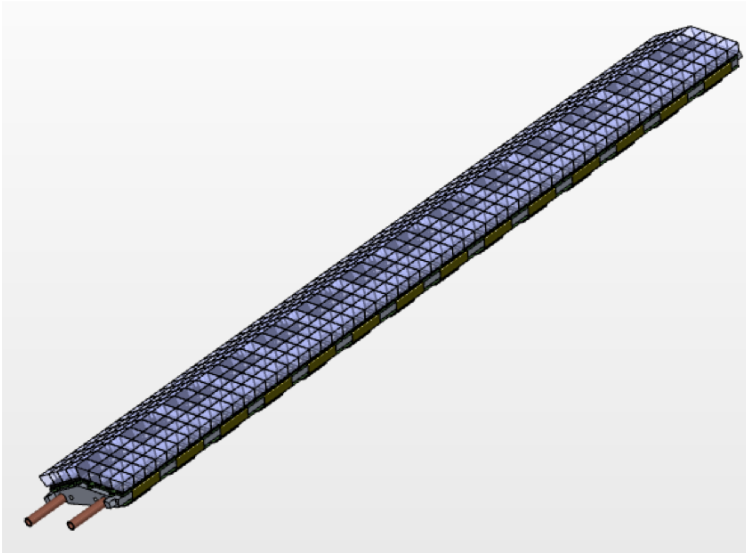
- 32 channel
- $3 \times 3 \text{ mm}^2$ SiPMs
- FEBA – flex printed PCB
- MuTrig ASIC in BGA package
- Scintillator tiles Ej-228 $\sim 6.5 \times 6.5 \times 5 \text{ mm}^3$, two type (center and edge)
- ESR reflected foil, individual tile wrapping



Detector overview

Module

- 14 submodule mounted on the cooling structure
- Water cooling
- 448 channels



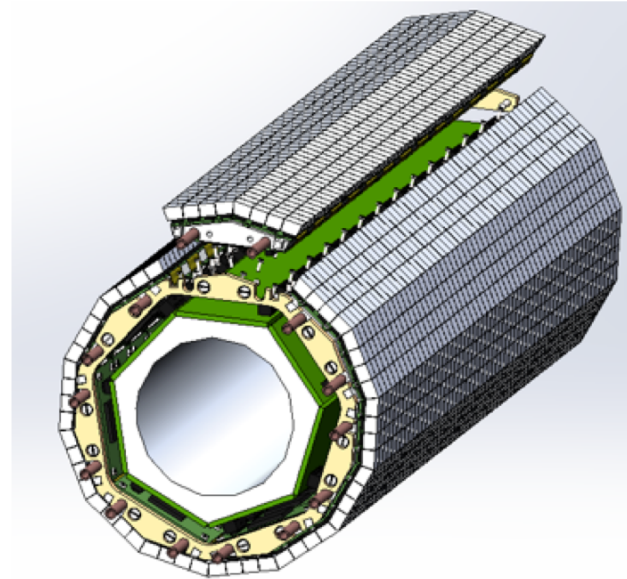
Detector overview

Recurl station

- 7 modules mounted on end rings
- Total length 36.8 cm
- 3136 channels

Full detector phase I

- 2 recurl station – total of 6272 channels

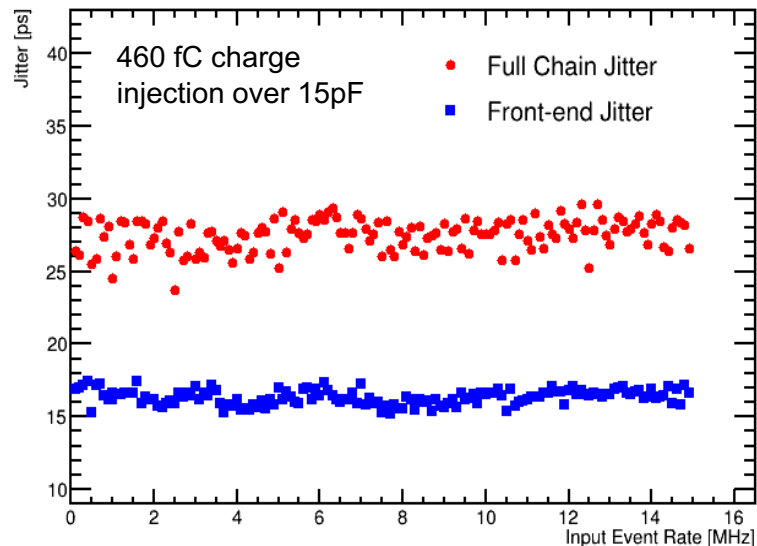
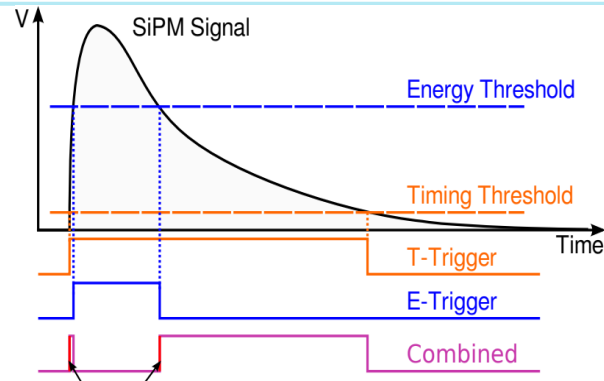


ASIC development

- 32 channels muTrig ASIC - developed in KIP HD (same front end of STiC 3.1)
- Gigabit serial data link (1.25 Gbps)

Two readout option:

- 48 bit/event (Tile detector):
 - both time and energy info
 - Event Rate limit: 20.24 MHz (632 kHz/ch)
- 27 bit/event (SciFi detector):
 - time info. + 1 bit energy info.
 - Event rate limit: 35MHz (1.1MHz/channel)



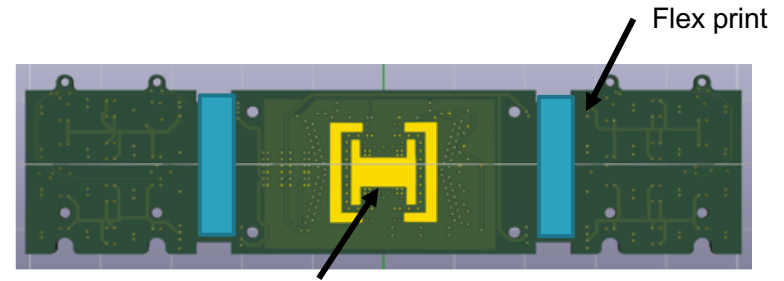
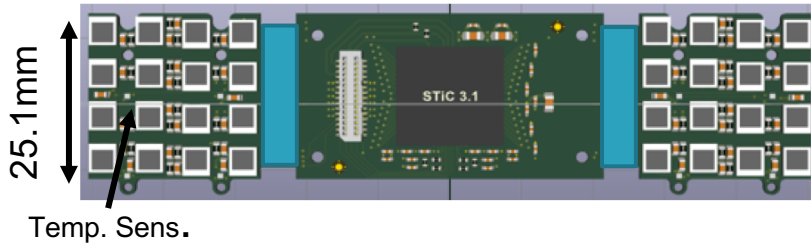
Technical prototype

Goals

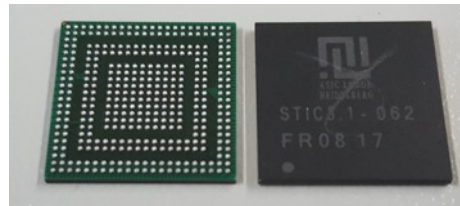
- Produce a module as close to design as possible
- Test mechanical support
- ASiC integration
- Cooling tests
- Learn and develop tools for assembly
- Develop test benches for detector characterization and quality control
- Measure detector performance
- Finalize detector design

Front-end board

- Develop and produce the front-end board in the summer 2017
- Using the STiC 3.1 packaged ASIC (not MuTrig)
- Hamamatsu SiPMs S13360-3050PE

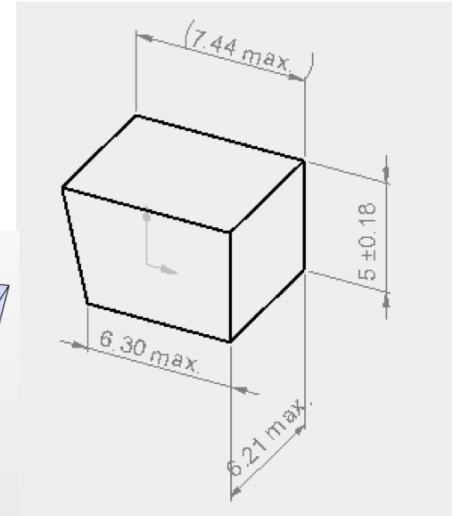
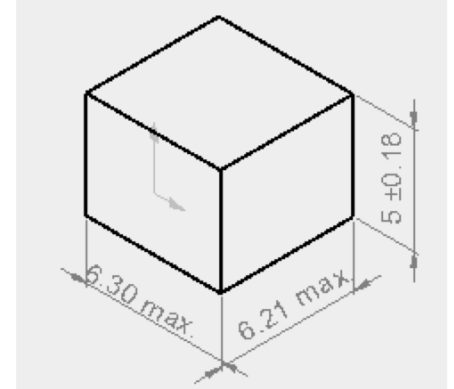
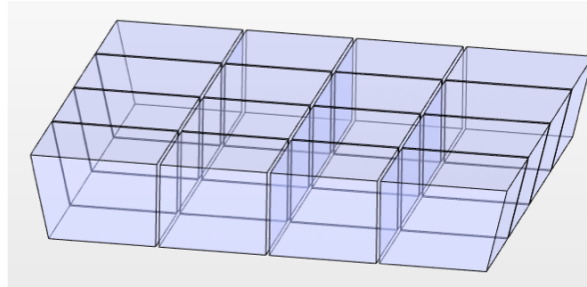
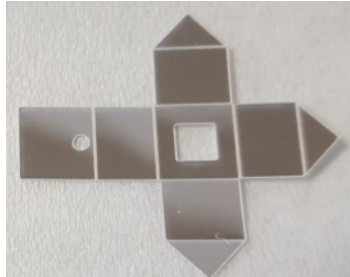
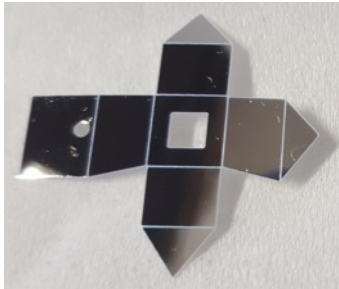


Test board for the packaged ASICs



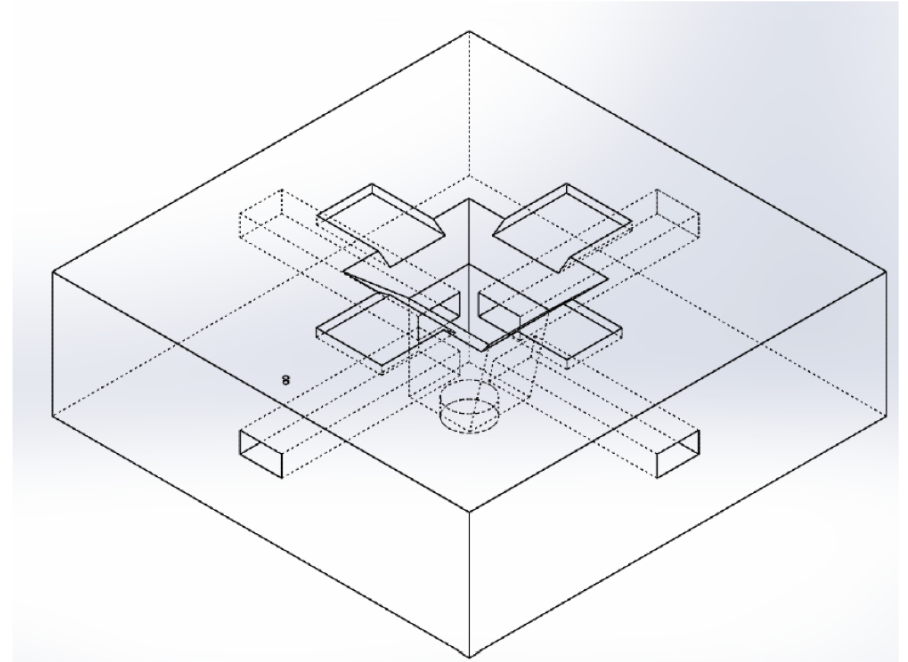
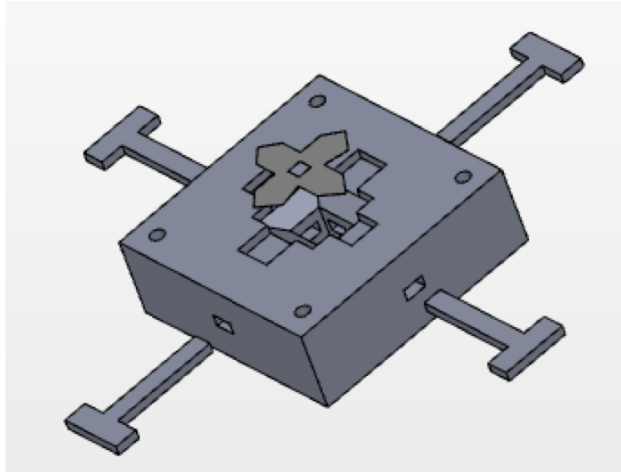
Tile individual wrapping

- Two type of tiles, Ej-228
- ESR 3M reflective foil
- The foil Foil design to maximize reflection
- Production in house using laser cutter
- Additional hole for monitoring the glue (might remove)
- The foil as a cover from the top and bottom

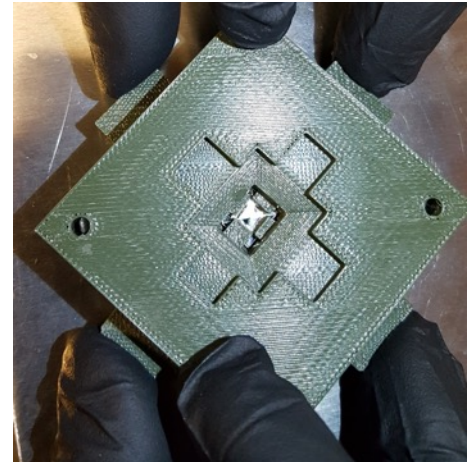
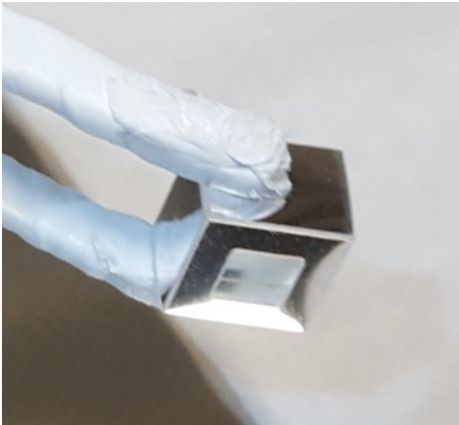
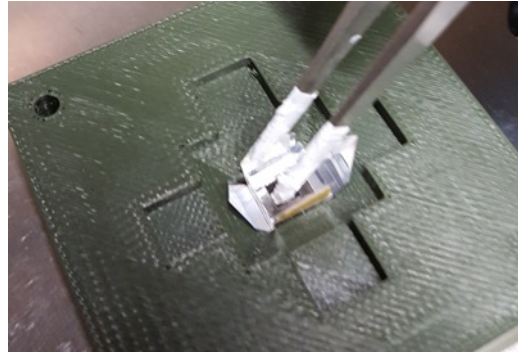
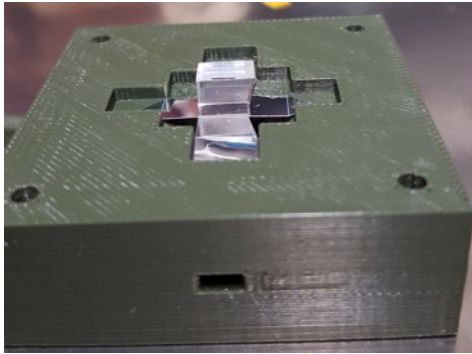


Wrapping tools

- Design 2 types of tools for different tile shapes
- 3D printed prototypes
- Will modified design for production

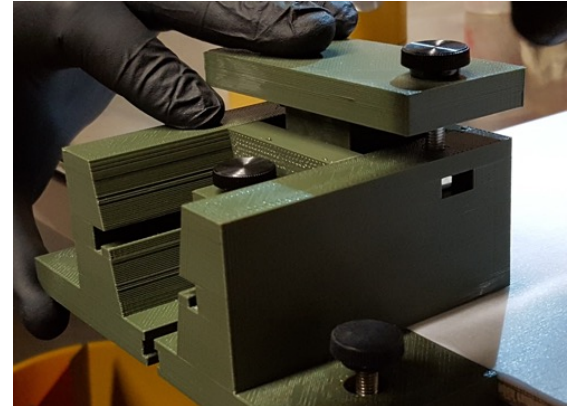
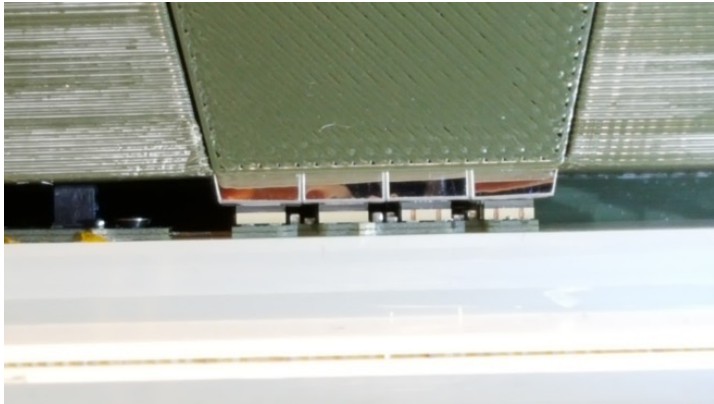
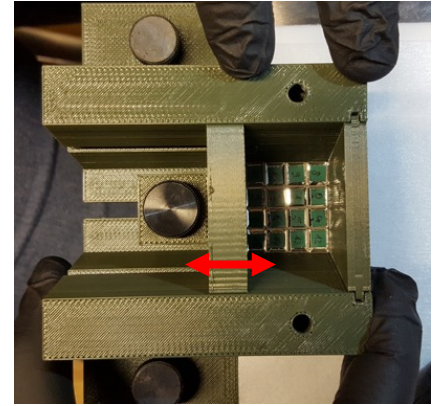
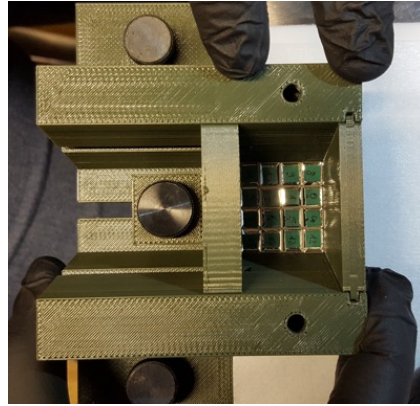
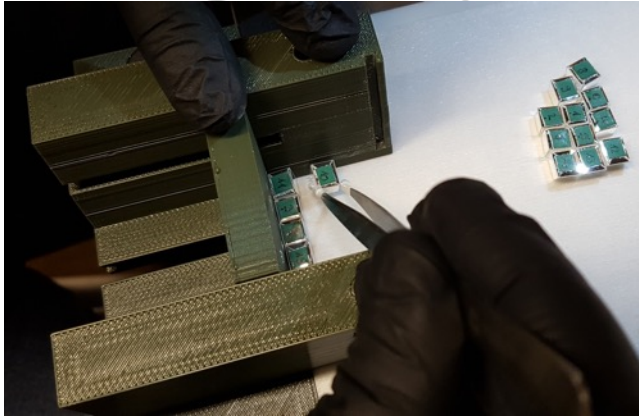


Tile wrapping procedure



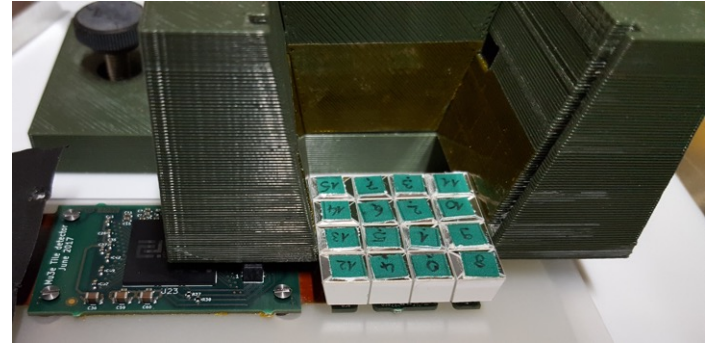
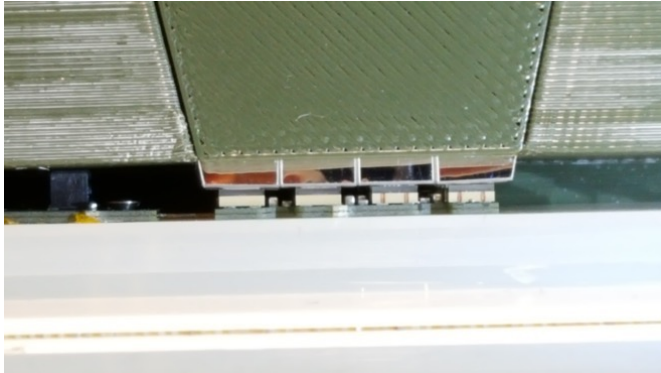
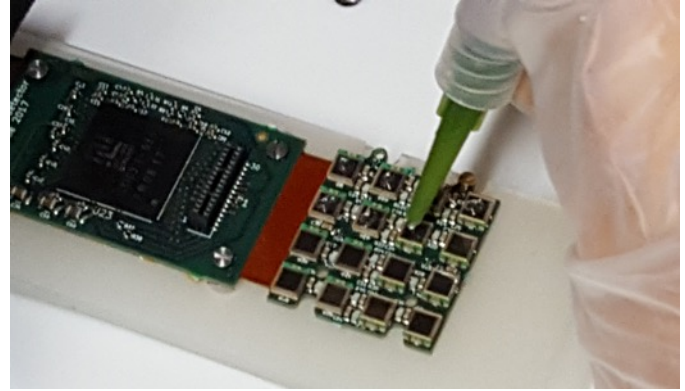
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Gluing tool and procedure



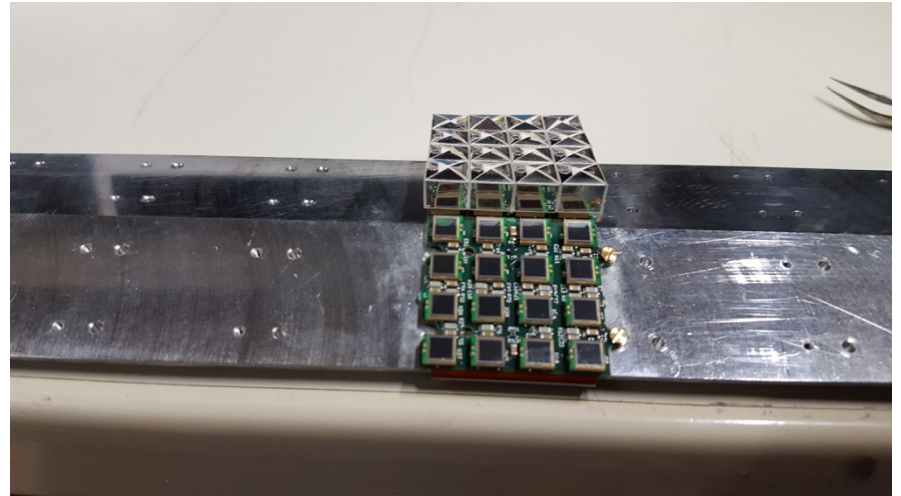
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Gluing tool and procedure



Assembly steps

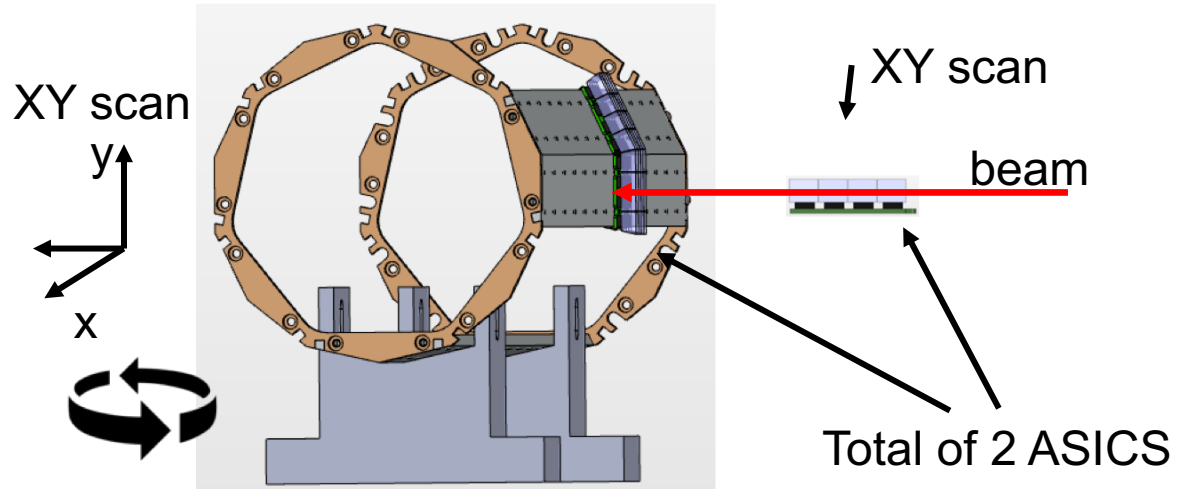
- ASIC test before equipping the PCB
- SiPM diode test before soldering
- DCR test of submodule with fully equipped board
- Wrapping of Tiles (each day for 4 submodule, single module ~1h)
- Gluing 4 submodule in parallel
- QA test in the lab



March 8, 2018

Test beam setup

- Two weeks ago at DESY
- Trigger – submodule parallel to beam (passes 4 tiles)
- DUT – perpendicular to beam with the option for rotation



Test beam setup

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- DUT – perpendicular to beam with the option for rotation

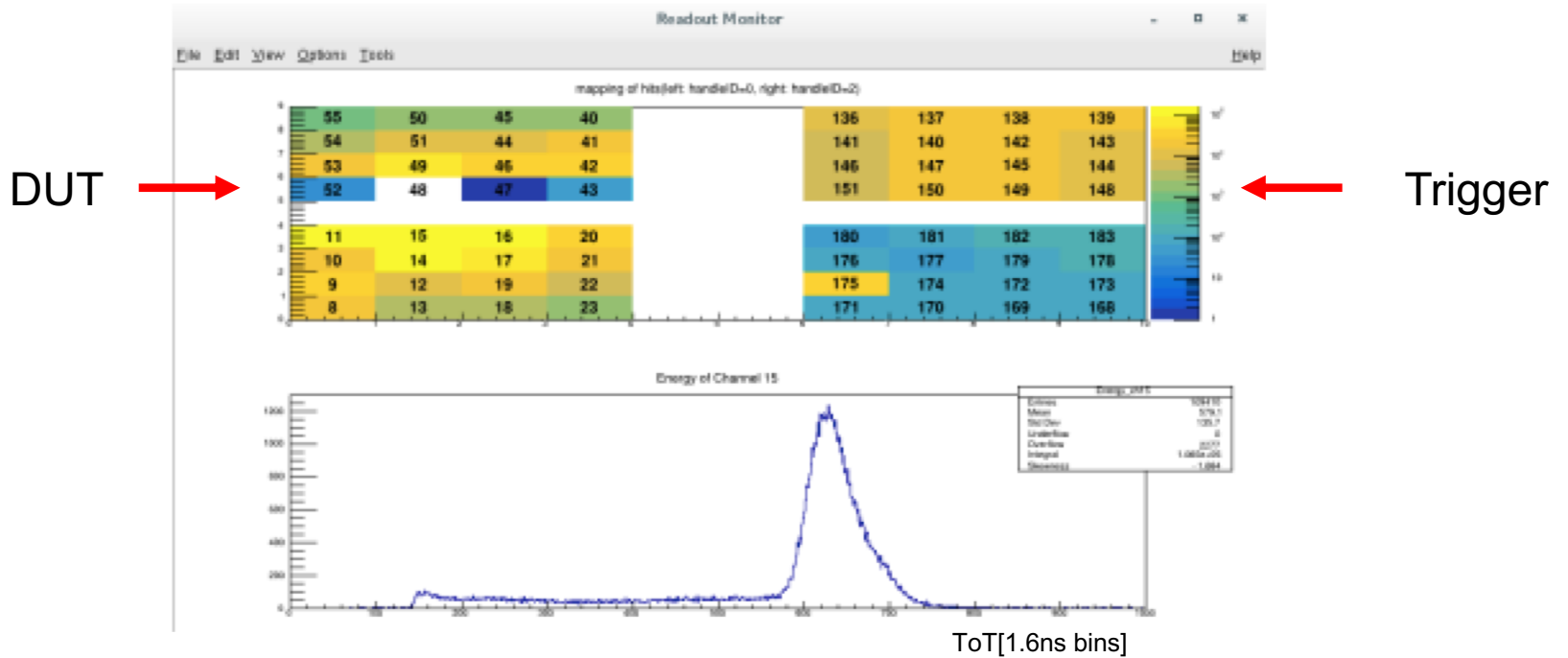
DUT
(one row
without tiles)



Trigger

Detector performance

- View from the online monitor

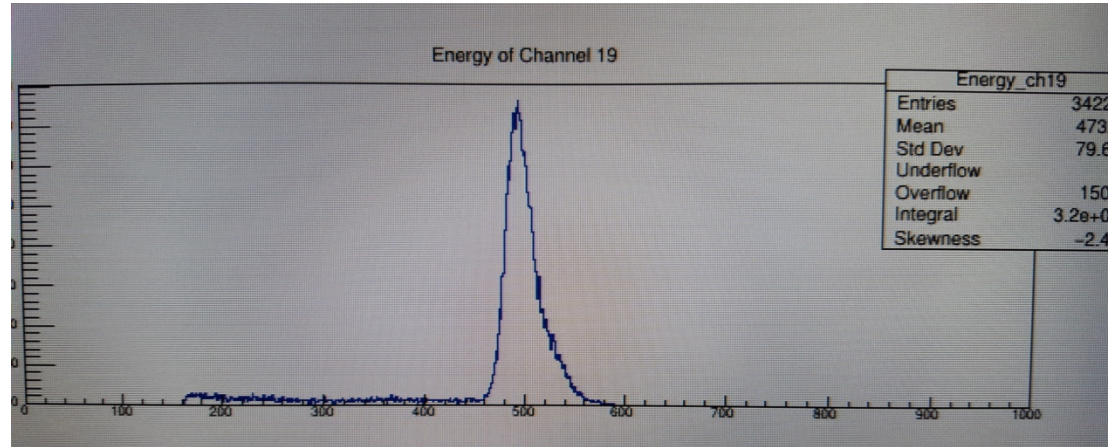
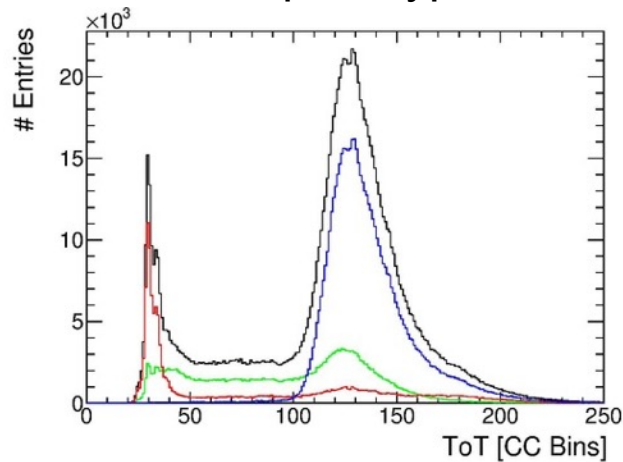


ToT spectrum

- ToT spectrum looks promising!
- Low crosstalk -> wrapping concept works!

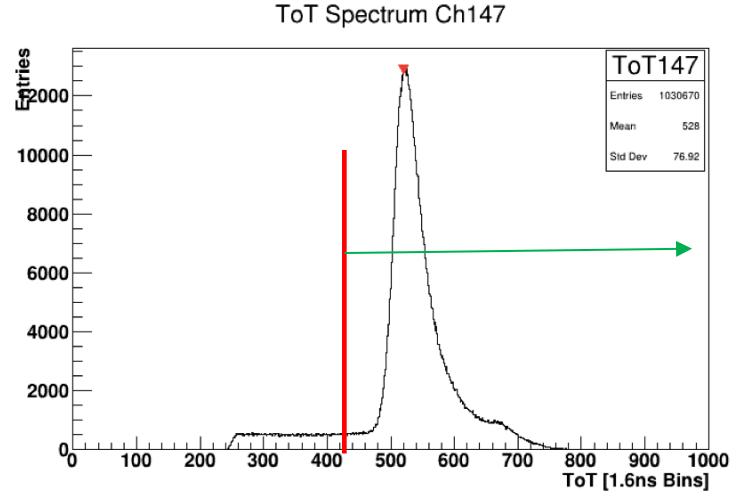
11	15	16	20
10	14	17	21
9	12	19	22
8	13	18	23

Old prototype



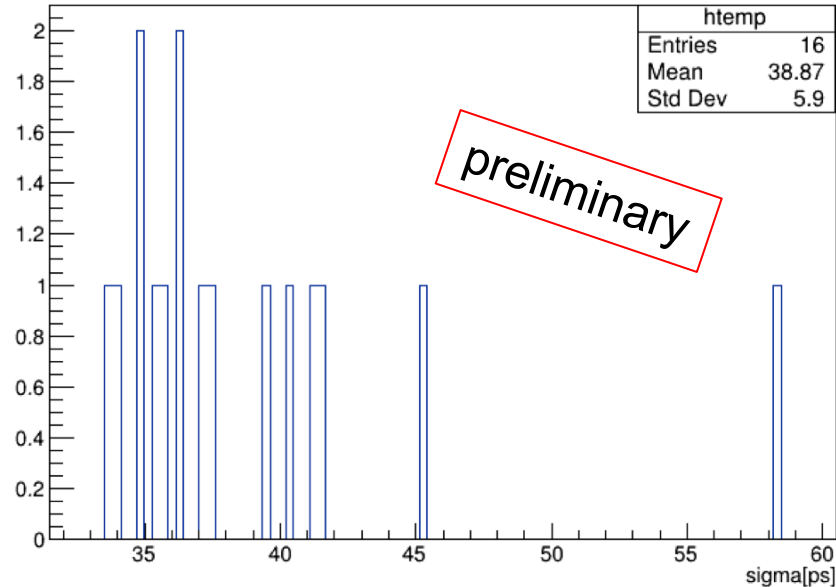
Trigger timing

- ASIC not optimize, only T-threshold scan
- Same HV for all channel
- Low energy cuts only ($\mu-3\sigma$) and no time walk correction



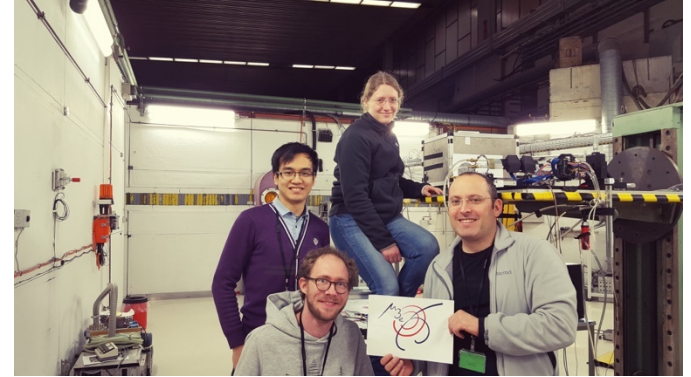
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Outlook

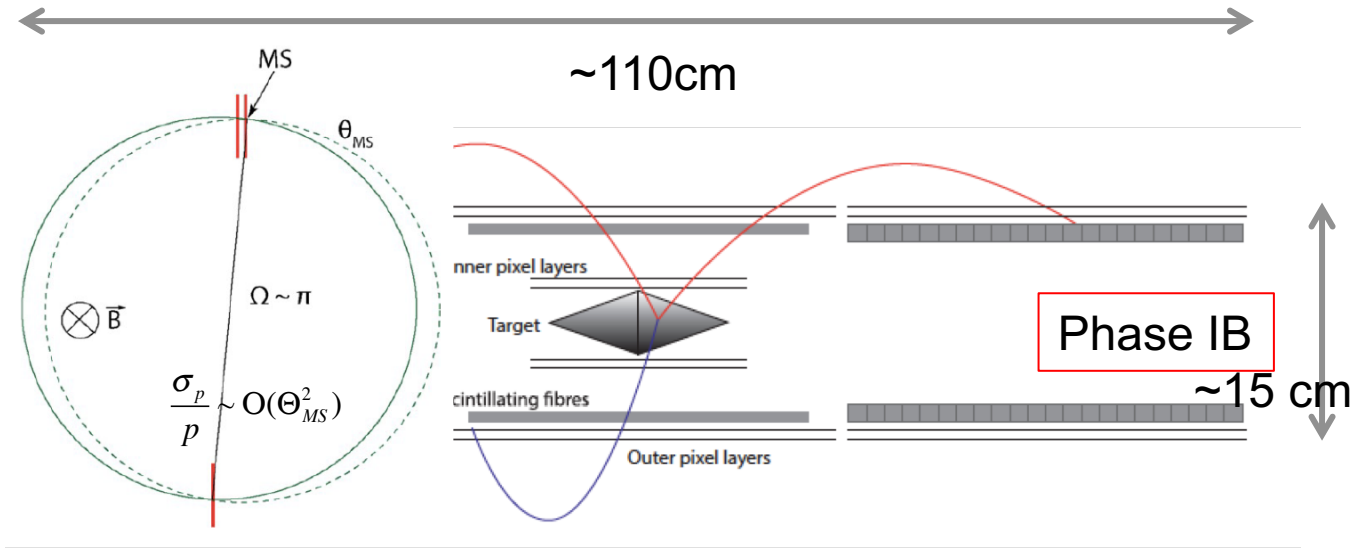
- Technical prototype with 96 channel was built
- Assembly tools were design and tested
- Assembly procedure will be finalize soon
- First results looks promising
- Next step - system readout integration
- Aim for vertical slice test by the end of the year (combine 3 detector system)

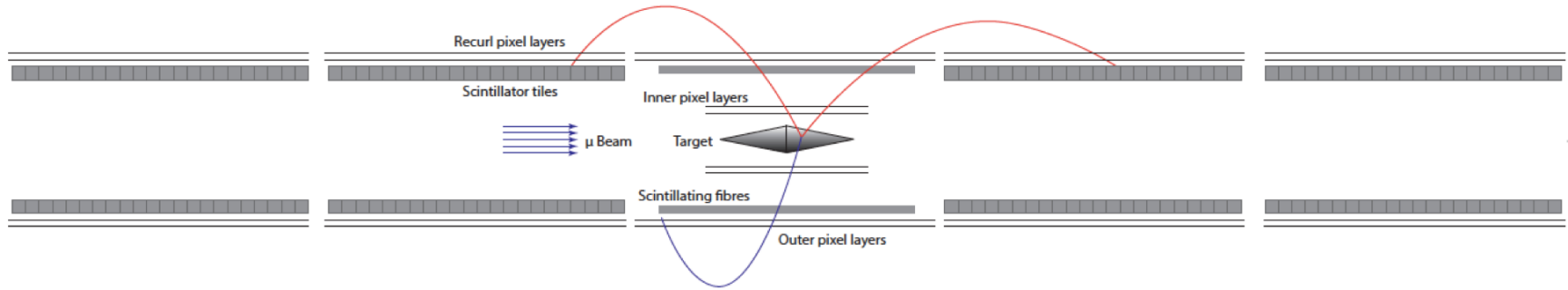


March 8, 2018

BK slides

Detector concept





Phase II

- PSI - **Muon beam $>10^9$ muons/s**
- Helium atmosphere
- 1 T B-field
- Target double hollow cone

MuTrig characterization

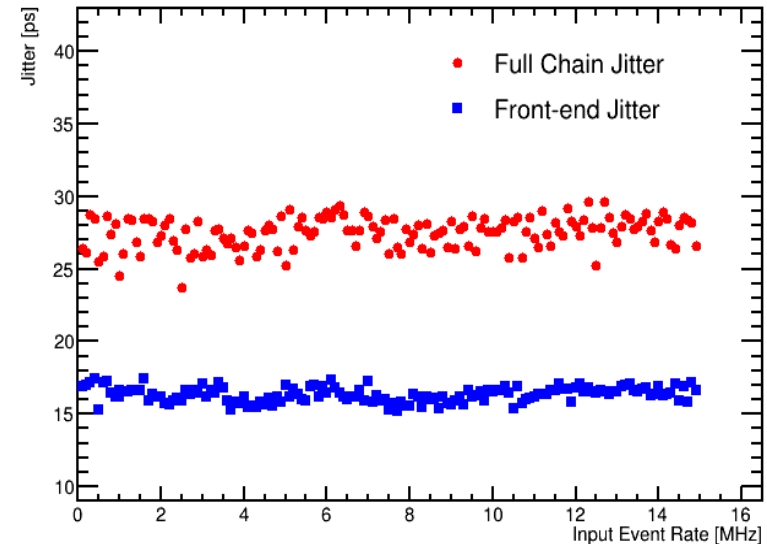
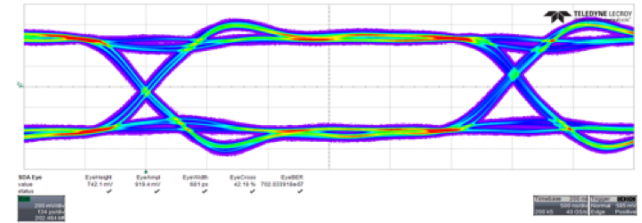
- Customized LVDS TX: Opened eye diagram with 8b/10b encoded RPBS data pattern @ 1.25 Gbps
- Bit Error Rate (BER) upper limit of $O(10^{-15})$ for bit rate up to 1.9 Gbps.

Two readout option:

- 48 bit/event (Tile detector):
 - both time and energy info
 - Event Rate limit: 20.24 MHz (632 kHz/ch)
- 27 bit/event (SciFi detector):
 - time info. + 1 bit energy info.
 - Event rate limit: 35MHz (1.1MHz/channel)

Jitter measurement:

- 460 fC charge injection over 15pF, input signal frequency up to 15MHz
- Use on-chip TDC for time stamp digitization



Detector overview

Submodule

- In total 32 channel
- $3 \times 3 \text{ mm}^2$ SiPMs
- FEBA – flex printed PCB
- MuTrig ASIC in BGA package
- Scintillator tiles Ej-228
~ $6.5 \times 6.5 \times 5 \text{ mm}^3$, two type (center and edge)
- ESR reflected foil, individual tile wrapping

Module

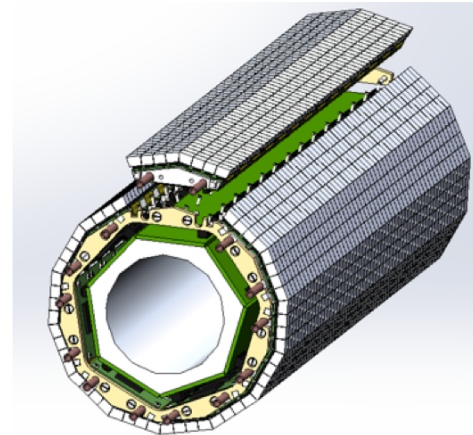
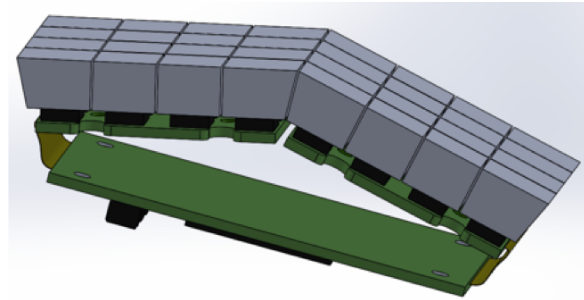
- 14 submodule mounted on the cooling structure
- Water cooling
- 448 channels

Recurl station

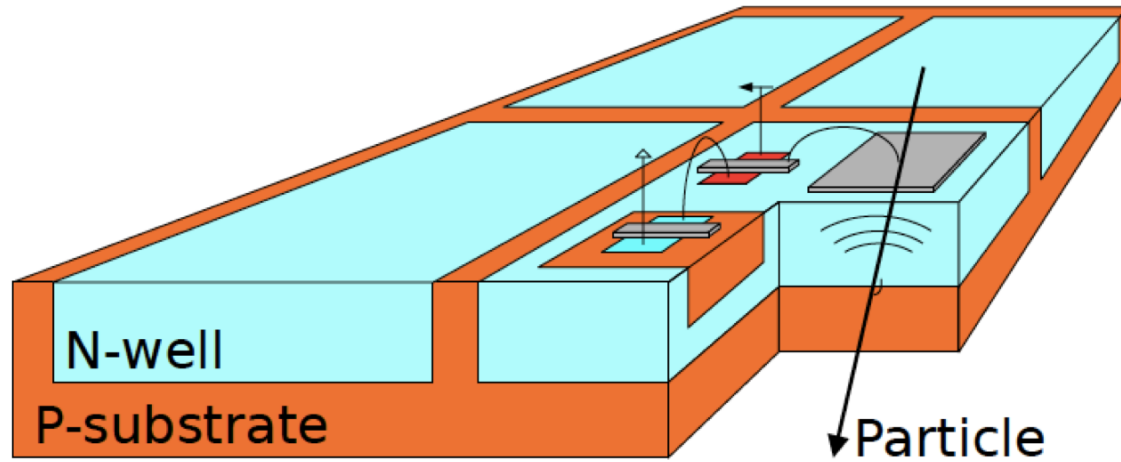
- 7 modules mounted on end rings
- Total length 36.8 cm
- 3136 channels

Full detector phase I

- 2 recurl station – total of 6272 channels



Pixel sensor

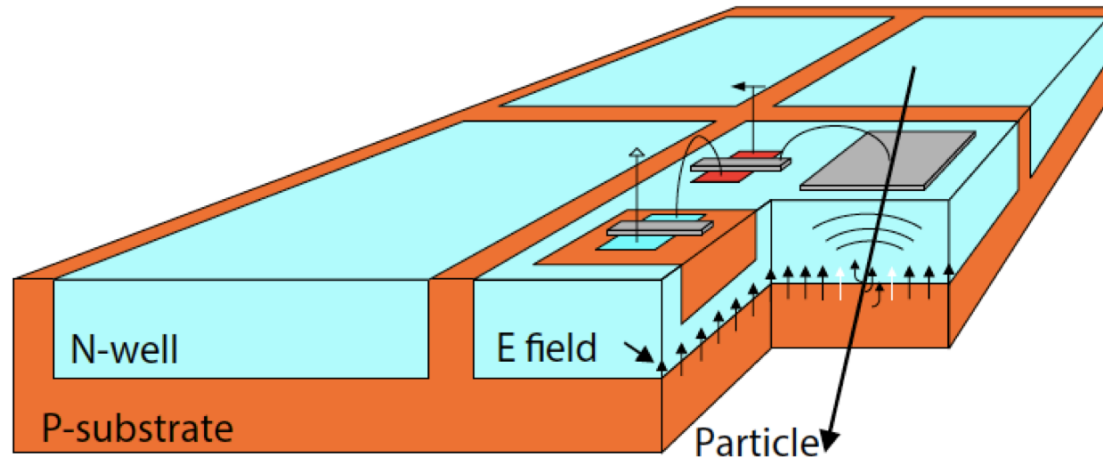


Ivan Perić, Nucl.Instrum.Meth. A582 (2007) 876-885

- ▶ Analog pixel electronics floats on sensor diode: **monolithic design**



Pixel sensor



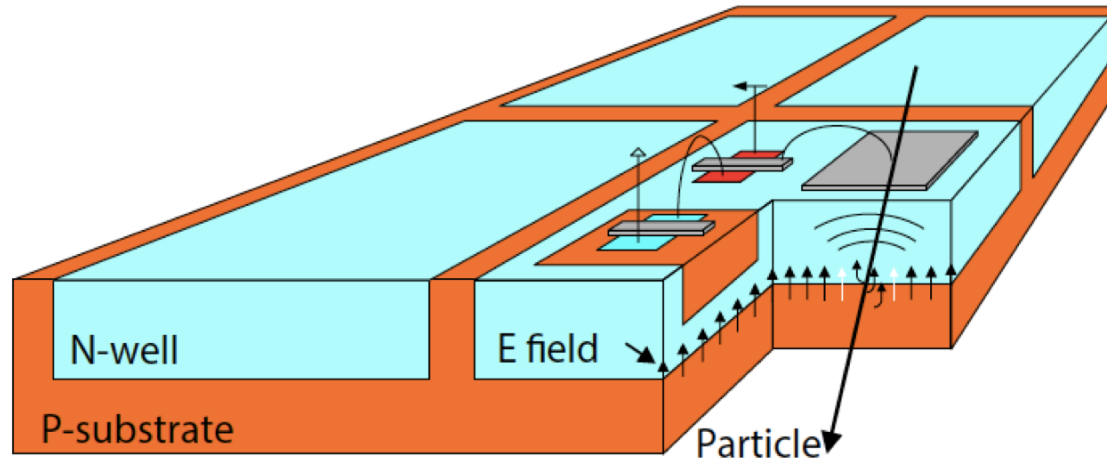
Ivan Perić, Nucl.Instrum.Meth. A582 (2007) 876-885

- ▶ Analog pixel electronics floats on sensor diode: **monolithic design**
- ▶ Industry standard HV CMOS process allows for E-field across diode \Rightarrow **depletion zone** of about 15 μm



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Pixel sensor



Ivan Perić, Nucl.Instrum.Meth. A582 (2007) 876-885

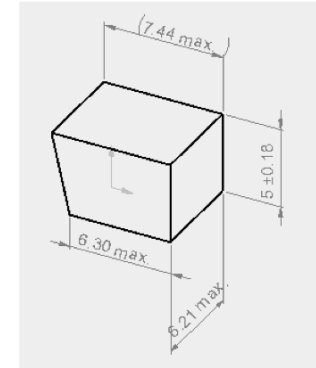
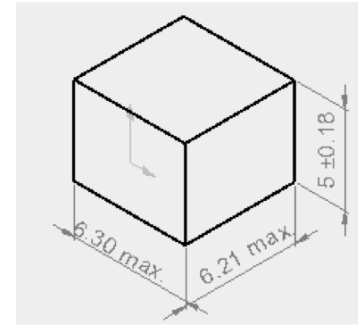
The MuPix chip is such a **depleted MAPS**, thinned to $50\ \mu\text{m} \approx 0.05\% x/X_0$



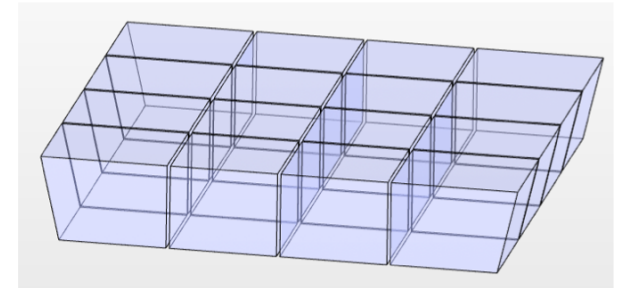
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Scintillator tiles

- Using EJ-228
- Two type of tiles:
 - Central tiles- rectangle shape (6.3x6.2x5.0mm³)
 - Edge tiles – trapezoidal shape (same base, top 7.44x6.2x5.0mm³)

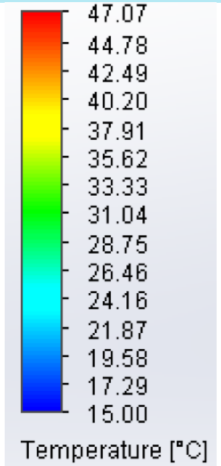
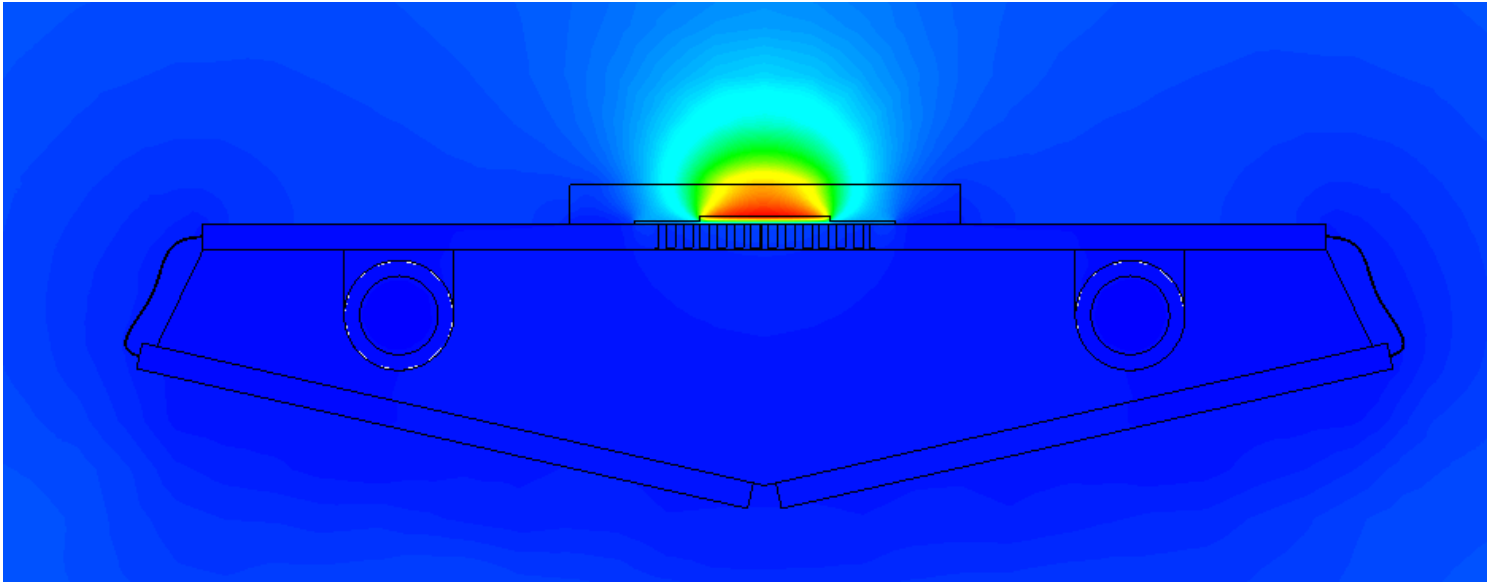


Properties	Value
Scintillation Efficiency (photons/1 MeV e ⁻)	10,200
Wavelength of Maximum Emission (nm)	391
Rise Time (ns)	0.5
Decay Time (ns)	1.4
Refractive Index	1.58
Coefficient of Linear Expansion	7.8×10^{-5} below 67°C
Light Output vs. Temperature	At 60°C, L.O. = 95% of that at 20°C No change from -60°C to 20°C
Softening point	75°C
Temperature Range	-20°C to 60°C

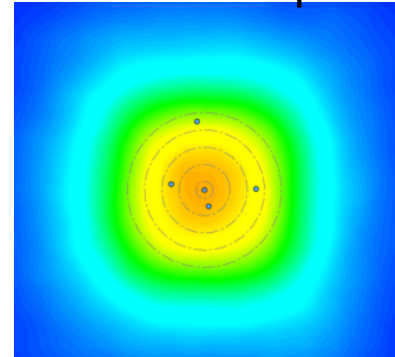


The technical prototype: Cooling studies

Example results for highest power consumption:

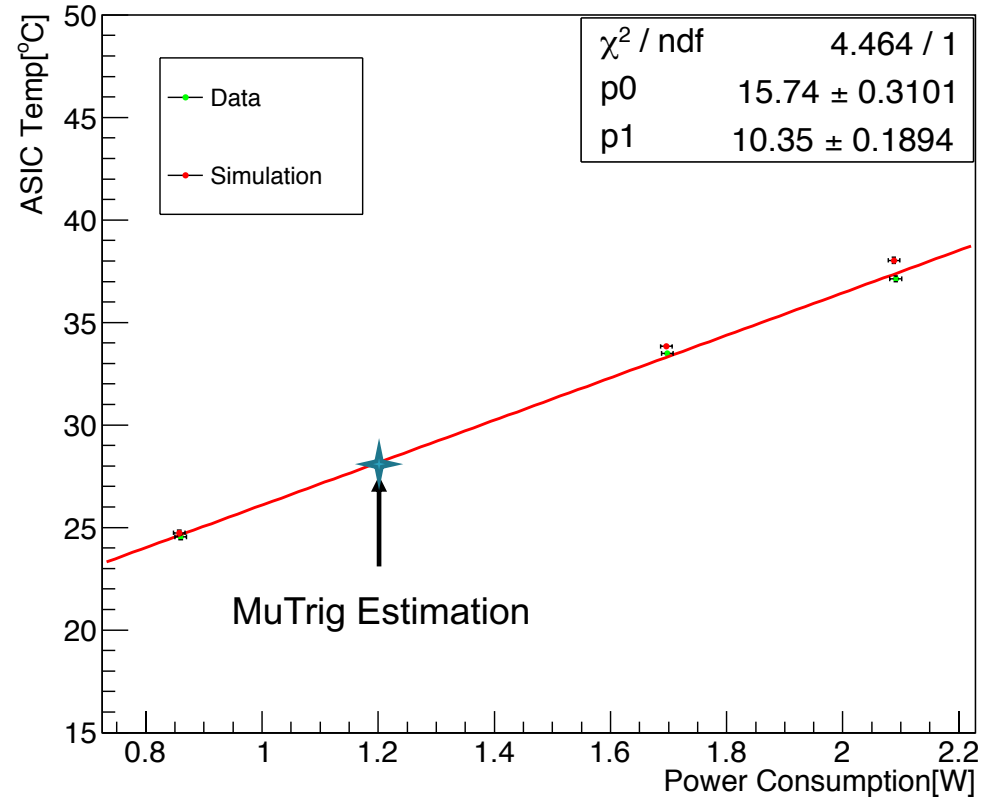


ASIC top



The technical prototype: Cooling studies

- Repeat at different power consumption of the ASIC
- Very good agreement to data ($<1^{\circ}\text{C}$)
- Small systematic error (Integration area of the temp. sensor is too small)
- Next step full module (ongoing)



Front-end board

- Develop and produce the front-end board in the summer 2017
- Using the STiC 3.1 packaged ASIC (not MuTrig)
- Hamamatsu SiPMs S13360-3050PE

